

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV

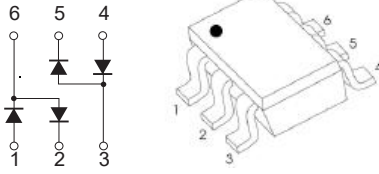


GDT



PLED

Product data sheet



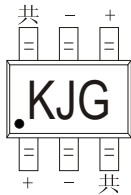
SOT-363

**BAV99DW**  
SWITCHING DIODE

**FEATURES**

- Fast Switching Speed
- Ultra-Small Surface Mount Package
- For General Purpose Switching Applications
- High Conductance

**MAKING: KJG**



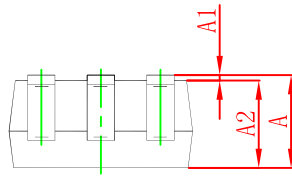
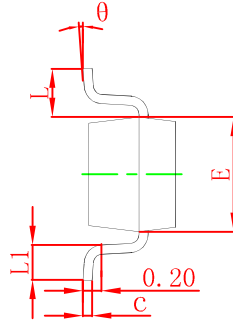
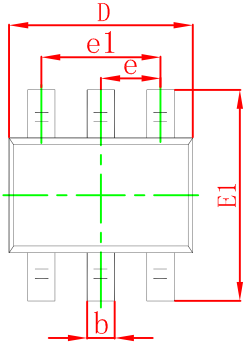
**Maximum Ratings @Ta=25°C**

Parameter	Symbol	Limit	Unit
Peak Repetitive Peak Reverse Voltage	$V_{RRM}$	75	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
Forward Continuous Current	$I_{FM}$	300	mA
Average Rectified Output Current	$I_O$	150	mA
Non-Repetitive Peak Forward Surge Current @ t=8.3 ms	$I_{FSM}$	2.0	A
Power Dissipation	$P_D$	200	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	625	°C/W
Operating Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55~+150	°C

**ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise specified)**

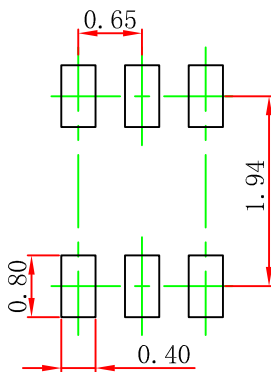
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage	$V_{(BR)}$	$I_R=2.5\mu A$	75			V
Reverse current	$I_R$	$V_R=75V$			2.5	$\mu A$
		$V_R=20V$			25	nA
Forward voltage	$V_F$	$I_F=1mA$			0.715	V
		$I_F=10mA$			0.855	
		$I_F=50mA$			1	
		$I_F=150mA$			1.25	
Total capacitance	$C_{tot}$	$V_R=0, f=1MHz$			2	pF
Reverse recovery time	$t_{rr}$	$I_F=I_R=10mA, I_{rr}=0.1 \times I_R, R_L=100\Omega$			4	ns

**SOT-363 Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

**SOT-363 Suggested Pad Layout**



**Note:**

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05mm.
3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
BAV99DW	SOT-363	3000

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